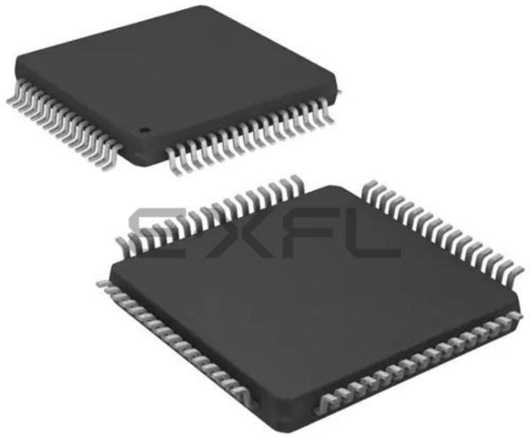

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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	40MHz
Connectivity	I²C, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, HLVD, POR, PWM, WDT
Number of I/O	54
Program Memory Size	96KB (48K x 16)
Program Memory Type	FLASH
EEPROM Size	1K x 8
RAM Size	3.8K x 8
Voltage - Supply (Vcc/Vdd)	2V ~ 5.5V
Data Converters	A/D 16x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	64-TQFP
Supplier Device Package	64-TQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic18lf6628-i-pt

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PIC18F8723 FAMILY

64/80-Pin, 1-Mbit, Enhanced Flash Microcontrollers with 12-Bit A/D and nanoWatt Technology

Peripheral Highlights:

- 12-Bit, Up to 16-Channel Analog-to-Digital Converter module (A/D):
  - Auto-acquisition capability
  - Conversion available during Sleep
- Two Master Synchronous Serial Port (MSSP) modules supporting 2/3/4-Wire SPI (all four modes) and I^2C™ Master and Slave modes
- Two Capture/Compare/PWM (CCP) modules
- Three Enhanced Capture/Compare/PWM (ECCP) modules:
  - One, two or four PWM outputs
  - Selectable polarity
  - Programmable dead time
  - Auto-shutdown and auto-restart
- Two Enhanced Addressable USART modules:
  - Supports RS-485, RS-232 and LIN 1.2
  - Auto-wake-up on Start bit
  - Auto-Baud Detect
- Dual Analog Comparators with Input Multiplexing
- High-Current Sink/Source 25 mA/25 mA
- Four Programmable External Interrupts
- Four Input Change Interrupts

External Memory Interface:

- Address Capability of Up to 2 Mbytes
- 8-Bit or 16-Bit Interface
- 8, 12, 16 and 20-Bit Address modes

Power-Managed Modes:

- Run: CPU on, Peripherals on
- Idle: CPU off, Peripherals on
- Sleep: CPU off, Peripherals off
- Idle mode Currents Down to 15 μA Typical
- Sleep Current Down to 0.2 μA Typical
- Timer1 Oscillator: 1.8 μA, 32 kHz, 2V
- Watchdog Timer: 2.1 μA

Special Microcontroller Features:

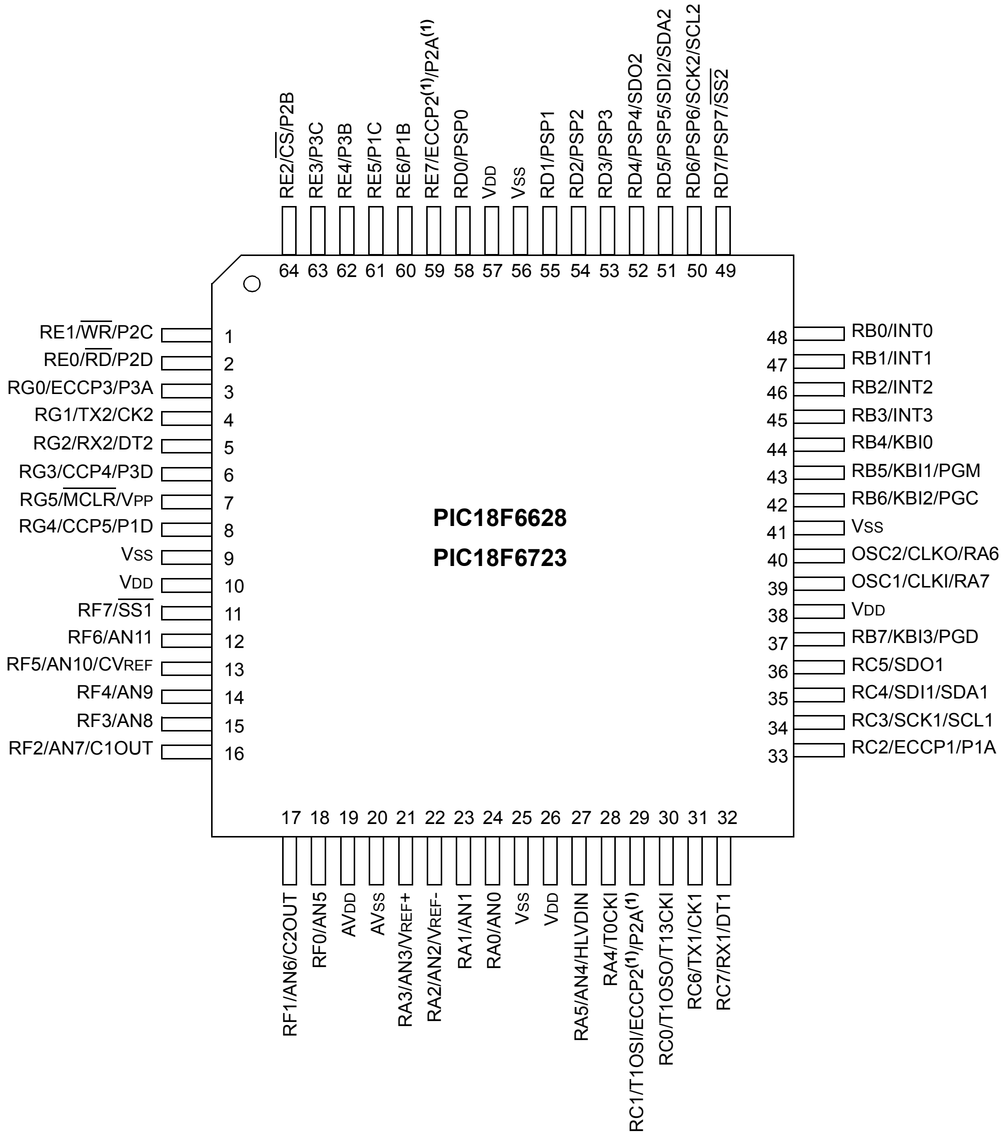
- C Compiler Optimized Architecture:
  - Optional extended instruction set designed to optimize re-entrant code
- 100,000 Erase/Write Cycle Enhanced Flash Program Memory Typical
- 1,000,000 Erase/Write Cycle Data EEPROM Memory Typical
- Flash/Data EEPROM Retention: 100 Years Typical
- Self-Programmable under Software Control
- Priority Levels for Interrupts
- 8 x 8 Single-Cycle Hardware Multiplier
- Extended Watchdog Timer (WDT):
  - Programmable period from 4 ms to 131s
- Single-Supply In-Circuit Serial Programming™ (ICSP™) via Two Pins
- In-Circuit Debug (ICD) via Two Pins
- Wide Operating Voltage Range: 2.0V to 5.5V
- Fail-Safe Clock Monitor
- Two-Speed Oscillator Start-up
- nanoWatt Technology

Note: This document is supplemented by the *"PIC18F8722 Family Data Sheet"* (DS39646). See **Section 1.0 "Device Overview"**.

Device	Program Memory		Data Memory		I/O	12-Bit A/D (ch)	CCP/ ECCP (PWM)	MSSP			EUSART	Comparators	Timers 8/16-Bit	External Bus
	Flash (bytes)	# Single-Word Instructions	SRAM (bytes)	EEPROM (bytes)					SPI	Master I^2C™				
PIC18F6628	96K	49152	3936	1024	54	12	2/3	2	Y	Y	2	2	2/3	N
PIC18F6723	128K	65536	3936	1024	54	12	2/3	2	Y	Y	2	2	2/3	N
PIC18F8628	96K	49152	3936	1024	70	16	2/3	2	Y	Y	2	2	2/3	Y
PIC18F8723	128K	65536	3936	1024	70	16	2/3	2	Y	Y	2	2	2/3	Y

Pin Diagrams

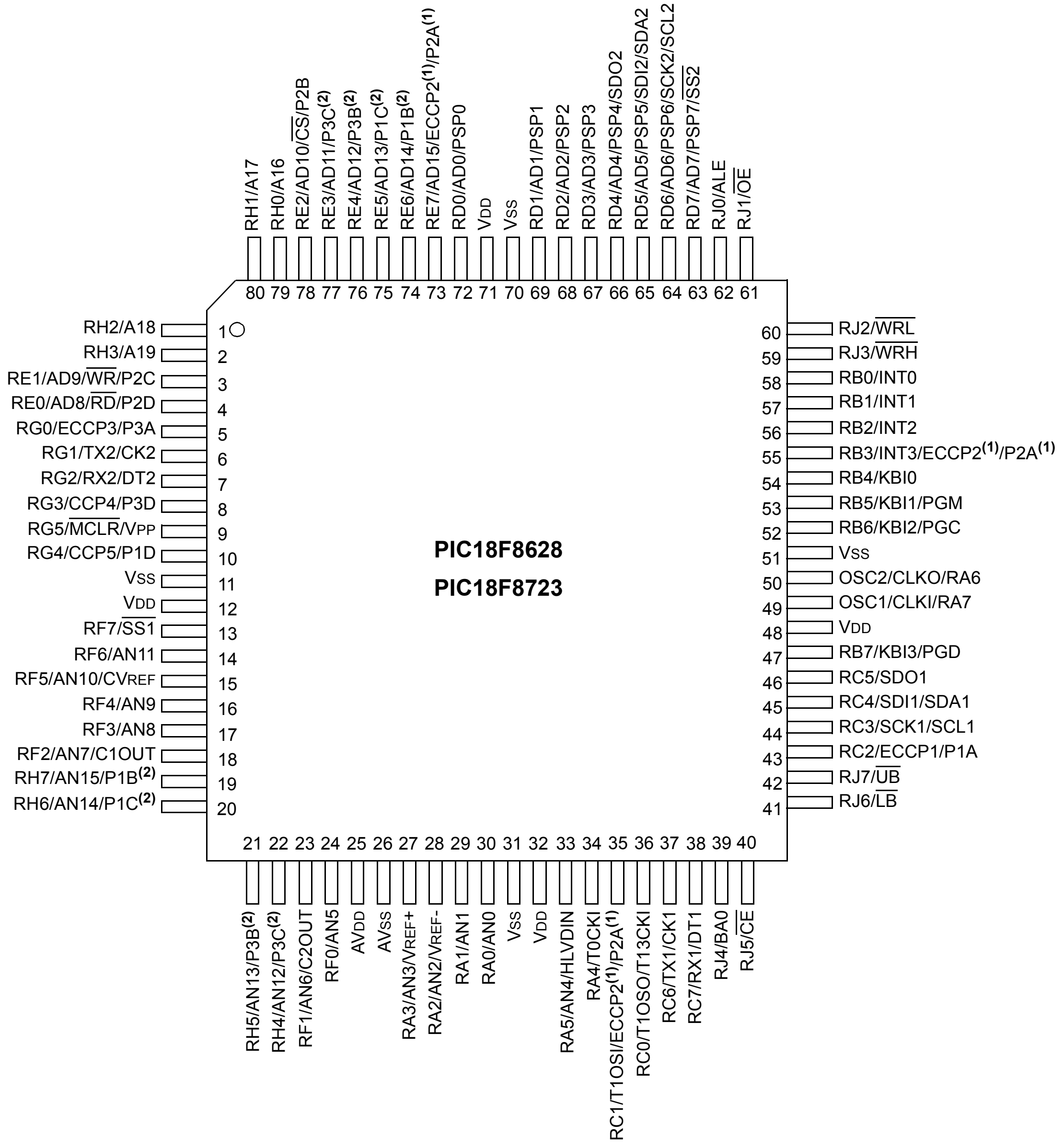
64-Pin TQFP



Note 1: The ECCP2/P2A pin placement is determined by the CCP2MX Configuration bit.

Pin Diagrams (Continued)

80-Pin TQFP



Note 1: The ECCP2/P2A pin placement is determined by the CCP2MX Configuration bit and Processor mode settings.

2: P1B, P1C, P3B and P3C pin placement is determined by the ECCPMX Configuration bit.

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NOTES:

TABLE 1-1: DEVICE FEATURES

Features	PIC18F6628	PIC18F6723	PIC18F8628	PIC18F8723
Operating Frequency	DC – 40 MHz	DC – 40 MHz	DC – 40 MHz	DC – 40 MHz
Program Memory (Bytes)	96K	128K	96K	128K
Program Memory (Instructions)	49152	65536	49152	65536
Data Memory (Bytes)	3936	3936	3936	3936
Data EEPROM Memory (Bytes)	1024	1024	1024	1024
Interrupt Sources	28	28	29	29
I/O Ports	Ports A, B, C, D, E, F, G	Ports A, B, C, D, E, F, G	Ports A, B, C, D, E, F, G, H, J	Ports A, B, C, D, E, F, G, H, J
Timers	5	5	5	5
Capture/Compare/PWM Modules	2	2	2	2
Enhanced Capture/Compare/ PWM Modules	3	3	3	3
Enhanced USART	2	2	2	2
Serial Communications	MSSP, Enhanced USART	MSSP, Enhanced USART	MSSP, Enhanced USART	MSSP, Enhanced USART
Parallel Communications (PSP)	Yes	Yes	Yes	Yes
12-Bit Analog-to-Digital Module	12 Input Channels	12 Input Channels	16 Input Channels	16 Input Channels
Resets (and Delays)	POR, BOR, `RESET` Instruction, Stack Full, Stack Underflow (PWRT, OST), $\overline{\text{MCLR}}$ (optional), WDT	POR, BOR, `RESET` Instruction, Stack Full, Stack Underflow (PWRT, OST), $\overline{\text{MCLR}}$ (optional), WDT	POR, BOR, `RESET` Instruction, Stack Full, Stack Underflow (PWRT, OST), $\overline{\text{MCLR}}$ (optional), WDT	POR, BOR, `RESET` Instruction, Stack Full, Stack Underflow (PWRT, OST), $\overline{\text{MCLR}}$ (optional), WDT
Programmable High/Low-Voltage Detect	Yes	Yes	Yes	Yes
Programmable Brown-out Reset	Yes	Yes	Yes	Yes
Instruction Set	75 Instructions; 83 with Extended Instruction Set Enabled	75 Instructions; 83 with Extended Instruction Set Enabled	75 Instructions; 83 with Extended Instruction Set Enabled	75 Instructions; 83 with Extended Instruction Set Enabled
Packages	64-Pin TQFP	64-Pin TQFP	80-Pin TQFP	80-Pin TQFP

TABLE 1-3: PIC18F8628/8723 (80-PIN) PINOUT I/O DESCRIPTIONS (CONTINUED)

Pin Name	Pin Number	Pin Type	Buffer Type	Description
	TQFP			
				PORTB is a bidirectional I/O port. PORTB can be software programmed for internal weak pull-ups on all inputs.
RB0/INT0/FLT0	58			
RB0		I/O	TTL	Digital I/O.
INT0		I	ST	External interrupt 0.
FLT0		I	ST	PWM Fault input for ECCPx.
RB1/INT1	57			
RB1		I/O	TTL	Digital I/O.
INT1		I	ST	External interrupt 1.
RB2/INT2	56			
RB2		I/O	TTL	Digital I/O.
INT2		I	ST	External interrupt 2.
RB3/INT3/ECCP2/P2A	55			
RB3		I/O	TTL	Digital I/O.
INT3		I	ST	External interrupt 3.
ECCP2[1]		O	—	Enhanced Capture 2 input/Compare 2 output/ PWM2 output.
P2A[1]		O	—	ECCP2 PWM output A.
RB4/KBI0	54			
RB4		I/O	TTL	Digital I/O.
KBI0		I	TTL	Interrupt-on-change pin.
RB5/KBI1/PGM	53			
RB5		I/O	TTL	Digital I/O.
KBI1		I	TTL	Interrupt-on-change pin.
PGM		I/O	ST	Low-Voltage ICSP™ Programming enable pin.
RB6/KBI2/PGC	52			
RB6		I/O	TTL	Digital I/O.
KBI2		I	TTL	Interrupt-on-change pin.
PGC		I/O	ST	In-Circuit Debugger and ICSP™ programming clock pin.
RB7/KBI3/PGD	47			
RB7		I/O	TTL	Digital I/O.
KBI3		I	TTL	Interrupt-on-change pin.
PGD		I/O	ST	In-Circuit Debugger and ICSP programming data pin.

Legend:
TTL = TTL compatible input
ST = Schmitt Trigger input with CMOS levels
I = Input
P = Power
CMOS = CMOS compatible input or output
Analog = Analog input
O = Output
I^2C™/SMB = I^2C/SMBus input buffer

Note 1: Alternate assignment for ECCP2 when Configuration bit, CCP2MX, is cleared (all operating modes except Microcontroller mode).
2: Default assignment for ECCP2 in all operating modes (CCP2MX is set).
3: Alternate assignment for ECCP2 when CCP2MX is cleared (Microcontroller mode only).
4: Default assignment for P1B/P1C/P3B/P3C (ECCPMX is set).
5: Alternate assignment for P1B/P1C/P3B/P3C (ECCPMX is clear).

TABLE 1-3: PIC18F8628/8723 (80-PIN) PINOUT I/O DESCRIPTIONS (CONTINUED)

Pin Name	Pin Number	Pin Type	Buffer Type	Description
	TQFP			
				PORTD is a bidirectional I/O port.
RD0/AD0/PSP0	72			
RD0		I/O	ST	Digital I/O.
AD0		I/O	TTL	External memory address/data 0.
PSP0		I/O	TTL	Parallel Slave Port data.
RD1/AD1/PSP1	69			
RD1		I/O	ST	Digital I/O.
AD1		I/O	TTL	External memory address/data 1.
PSP1		I/O	TTL	Parallel Slave Port data.
RD2/AD2/PSP2	68			
RD2		I/O	ST	Digital I/O.
AD2		I/O	TTL	External memory address/data 2.
PSP2		I/O	TTL	Parallel Slave Port data.
RD3/AD3/PSP3	67			
RD3		I/O	ST	Digital I/O.
AD3		I/O	TTL	External memory address/data 3.
PSP3		I/O	TTL	Parallel Slave Port data.
RD4/AD4/PSP4/SDO2	66			
RD4		I/O	ST	Digital I/O.
AD4		I/O	TTL	External memory address/data 4.
PSP4		I/O	TTL	Parallel Slave Port data.
SDO2		O	—	SPI data out.
RD5/AD5/PSP5/ SDI2/SDA2	65			
RD5		I/O	ST	Digital I/O.
AD5		I/O	TTL	External memory address/data 5.
PSP5		I/O	TTL	Parallel Slave Port data.
SDI2		I	ST	SPI data in.
SDA2		I/O	I^{2}C/SMB	I^{2}C™ data I/O.
RD6/AD6/PSP6/ SCK2/SCL2	64			
RD6		I/O	ST	Digital I/O.
AD6		I/O	TTL	External memory address/data 6.
PSP6		I/O	TTL	Parallel Slave Port data.
SCK2		I/O	ST	Synchronous serial clock input/output for SPI mode.
SCL2		I/O	I^{2}C/SMB	Synchronous serial clock input/output for I^{2}C mode.
RD7/AD7/PSP7/$\overline{\text{SS2}}$	63			
RD7		I/O	ST	Digital I/O.
AD7		I/O	TTL	External memory address/data 7.
PSP7		I/O	TTL	Parallel Slave Port data.
$\overline{\text{SS2}}$		I	TTL	SPI slave select input.

Legend:
TTL = TTL compatible input
ST = Schmitt Trigger input with CMOS levels
I = Input
P = Power
CMOS = CMOS compatible input or output
Analog = Analog input
O = Output
I^{2}C™/SMB = I^{2}C/SMBus input buffer

Note 1: Alternate assignment for ECCP2 when Configuration bit, CCP2MX, is cleared (all operating modes except Microcontroller mode).
2: Default assignment for ECCP2 in all operating modes (CCP2MX is set).
3: Alternate assignment for ECCP2 when CCP2MX is cleared (Microcontroller mode only).
4: Default assignment for P1B/P1C/P3B/P3C (ECCPMX is set).
5: Alternate assignment for P1B/P1C/P3B/P3C (ECCPMX is clear).

TABLE 1-3: PIC18F8628/8723 (80-PIN) PINOUT I/O DESCRIPTIONS (CONTINUED)

Pin Name	Pin Number	Pin Type	Buffer Type	Description
	TQFP			
				PORTE is a bidirectional I/O port.
RE0/AD8/$\overline{RD}$/P2D	4			
RE0		I/O	ST	Digital I/O.
AD8		I/O	TTL	External memory address/data 8.
$\overline{RD}$		I	TTL	Read control for Parallel Slave Port.
P2D		O	—	ECCP2 PWM output D.
RE1/AD9/$\overline{WR}$/P2C	3			
RE1		I/O	ST	Digital I/O.
AD9		I/O	TTL	External memory address/data 9.
$\overline{WR}$		I	TTL	Write control for Parallel Slave Port.
P2C		O	—	ECCP2 PWM output C.
RE2/AD10/$\overline{CS}$/P2B	78			
RE2		I/O	ST	Digital I/O.
AD10		I/O	TTL	External memory address/data 10.
$\overline{CS}$		I	TTL	Chip select control for Parallel Slave Port.
P2B		O	—	ECCP2 PWM output B.
RE3/AD11/P3C	77			
RE3		I/O	ST	Digital I/O.
AD11		I/O	TTL	External memory address/data 11.
P3C**(4)**		O	—	ECCP3 PWM output C.
RE4/AD12/P3B	76			
RE4		I/O	ST	Digital I/O.
AD12		I/O	TTL	External memory address/data 12.
P3B**(4)**		O	—	ECCP3 PWM output B.
RE5/AD13/P1C	75			
RE5		I/O	ST	Digital I/O.
AD13		I/O	TTL	External memory address/data 13.
P1C**(4)**		O	—	ECCP1 PWM output C.
RE6/AD14/P1B	74			
RE6		I/O	ST	Digital I/O.
AD14		I/O	TTL	External memory address/data 14.
P1B**(4)**		O	—	ECCP1 PWM output B.
RE7/AD15/ECCP2/ P2A	73			
RE7		I/O	ST	Digital I/O.
AD15		I/O	TTL	External memory address/data 15.
ECCP2**(3)**		I/O	ST	Enhanced Capture 2 input/Compare 2 output/ PWM2 output.
P2A**(3)**		O	—	ECCP2 PWM output A.

Legend:
TTL = TTL compatible input
ST = Schmitt Trigger input with CMOS levels
I = Input
P = Power
CMOS = CMOS compatible input or output
Analog = Analog input
O = Output
I^2C™/SMB = I^2C/SMBus input buffer

Note 1: Alternate assignment for ECCP2 when Configuration bit, CCP2MX, is cleared (all operating modes except Microcontroller mode).
2: Default assignment for ECCP2 in all operating modes (CCP2MX is set).
3: Alternate assignment for ECCP2 when CCP2MX is cleared (Microcontroller mode only).
4: Default assignment for P1B/P1C/P3B/P3C (ECCPMX is set).
5: Alternate assignment for P1B/P1C/P3B/P3C (ECCPMX is clear).

TABLE 1-3: PIC18F8628/8723 (80-PIN) PINOUT I/O DESCRIPTIONS (CONTINUED)

Pin Name	Pin Number	Pin Type	Buffer Type	Description
	TQFP			
				PORTH is a bidirectional I/O port.
RH0/A16	79			
RH0		I/O	ST	Digital I/O.
A16		I/O	TTL	External memory address/data 16.
RH1/A17	80			
RH1		I/O	ST	Digital I/O.
A17		I/O	TTL	External memory address/data 17.
RH2/A18	1			
RH2		I/O	ST	Digital I/O.
A18		I/O	TTL	External memory address/data 18.
RH3/A19	2			
RH3		I/O	ST	Digital I/O.
A19		I/O	TTL	External memory address/data 19.
RH4/AN12/P3C	22			
RH4		I/O	ST	Digital I/O.
AN12		I	Analog	Analog input 12.
P3C(5)		O	—	ECCP3 PWM output C.
RH5/AN13/P3B	21			
RH5		I/O	ST	Digital I/O.
AN13		I	Analog	Analog input 13.
P3B(5)		O	—	ECCP3 PWM output B.
RH6/AN14/P1C	20			
RH6		I/O	ST	Digital I/O.
AN14		I	Analog	Analog input 14.
P1C(5)		O	—	ECCP1 PWM output C.
RH7/AN15/P1B	19			
RH7		I/O	ST	Digital I/O.
AN15		I	Analog	Analog input 15.
P1B(5)		O	—	ECCP1 PWM output B.

Legend:

TTL = TTL compatible input

ST = Schmitt Trigger input with CMOS levels

I = Input

P = Power

CMOS = CMOS compatible input or output

Analog = Analog input

O = Output

I^2C™/SMB = I^2C/SMBus input buffer

Note 1: Alternate assignment for ECCP2 when Configuration bit, CCP2MX, is cleared (all operating modes except Microcontroller mode).

2: Default assignment for ECCP2 in all operating modes (CCP2MX is set).

3: Alternate assignment for ECCP2 when CCP2MX is cleared (Microcontroller mode only).

4: Default assignment for P1B/P1C/P3B/P3C (ECCPMX is set).

5: Alternate assignment for P1B/P1C/P3B/P3C (ECCPMX is clear).

2.2 Selecting and Configuring Acquisition Time

The ADCON2 register allows the user to select an acquisition time that occurs each time the GO/$\overline{\text{DONE}}$ bit is set. It also gives users the option to use an automatically determined acquisition time.

Acquisition time may be set with the ACQT2:ACQT0 bits (ADCON2<5:3>), which provide a range of 2 to 20 TAD. When the GO/$\overline{\text{DONE}}$ bit is set, the A/D module continues to sample the input for the selected acquisition time, then automatically begins a conversion. Since the acquisition time is programmed, there may be no need to wait for an acquisition time between selecting a channel and setting the GO/$\overline{\text{DONE}}$ bit.

Manual acquisition is selected when ACQT2:ACQT0 = `000`. When the GO/$\overline{\text{DONE}}$ bit is set, sampling is stopped and a conversion begins. The user is responsible for ensuring the required acquisition time has passed between selecting the desired input channel and setting the GO/$\overline{\text{DONE}}$ bit. This option is also the default Reset state of the ACQT2:ACQT0 bits and is compatible with devices that do not offer programmable acquisition times.

In either case, when the conversion is completed, the GO/$\overline{\text{DONE}}$ bit is cleared, the ADIF flag is set and the A/D begins sampling the currently selected channel again. If an acquisition time is programmed, there is nothing to indicate if the acquisition time has ended or if the conversion has begun.

2.3 Selecting the A/D Conversion Clock

The A/D conversion time per bit is defined as TAD. The A/D conversion requires 13 TAD per 12-bit conversion. The source of the A/D conversion clock is software selectable. There are seven possible options for TAD:

- 2 TOSC
- 4 TOSC
- 8 TOSC
- 16 TOSC
- 32 TOSC
- 64 TOSC
- Internal RC Oscillator

For correct A/D conversions, the A/D conversion clock (TAD) must be as short as possible, but greater than the minimum TAD (see parameter 130 for more information).

Table 2-1 shows the resultant TAD times derived from the device operating frequencies and the A/D clock source selected.

TABLE 2-1: TAD vs. DEVICE OPERATING FREQUENCIES

A/D Clock Source (TAD)		Assumes TAD Min. = 0.8 µs
Operation	**ADCS2:ADCS0**	**Maximum FOSC**
2 TOSC	`000`	2.50 MHz
4 TOSC	`100`	5.00 MHz
8 TOSC	`001`	10.00 MHz
16 TOSC	`101`	20.00 MHz
32 TOSC	`010`	40.00 MHz
64 TOSC	`110`	40.00 MHz
RC(1)	`x11`	1.00 MHz(2)

Note 1: The RC source has a typical TAD time of 2.5 µs.

2: For device frequencies above 1 MHz, the device must be in Sleep for the entire conversion or a FOSC divider should be used instead; otherwise, the A/D accuracy specification may not be met.

2.6 A/D Conversions

Figure 2-4 shows the operation of the A/D Converter after the GO/$\overline{\text{DONE}}$ bit has been set and the ACQT2:ACQT0 bits are cleared. A conversion is started after the following instruction to allow entry into Sleep mode before the conversion begins.

Figure 2-5 shows the operation of the A/D Converter after the GO/$\overline{\text{DONE}}$ bit has been set, the ACQT2:ACQT0 bits are set to '`010`' and a 4 TAD acquisition time has been selected before the conversion starts.

Clearing the GO/$\overline{\text{DONE}}$ bit during a conversion will abort the current conversion. The A/D Result register pair will NOT be updated with the partially completed A/D conversion sample. This means the ADRESH:ADRESL registers will continue to contain the value of the last completed conversion (or the last value written to the ADRESH:ADRESL registers).

After the A/D conversion is completed or aborted, a 2 TCY wait is required before the next acquisition can be started. After this wait, acquisition on the selected channel is automatically started.

Note: The GO/$\overline{\text{DONE}}$ bit should **NOT** be set in the same instruction that turns on the A/D. Code should wait at least 2 μs after enabling the A/D before beginning an acquisition and conversion cycle.

2.7 Discharge

The discharge phase is used to initialize the value of the holding capacitor. The array is discharged before every sample. This feature helps to optimize the unity gain amplifier, as the circuit always needs to charge the capacitor array, rather than charge/discharge based on previous measure values.

FIGURE 2-4: A/D CONVERSION TAD CYCLES (ACQT<2:0> = `000`, TACQ = `0`)

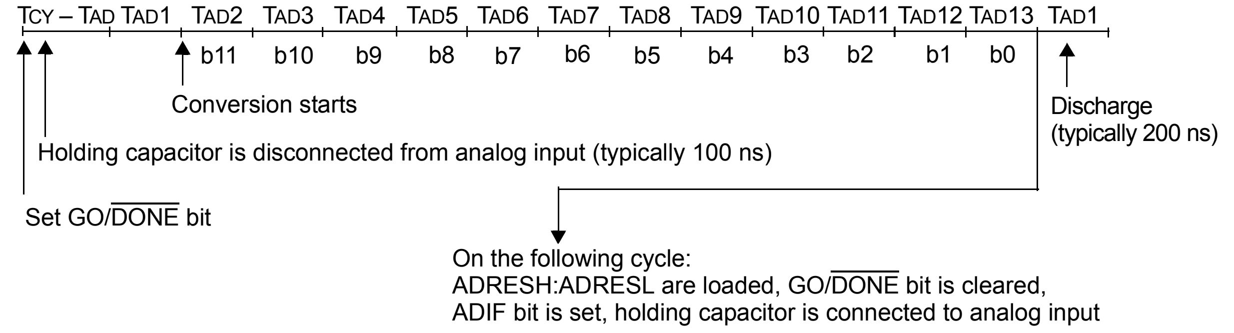
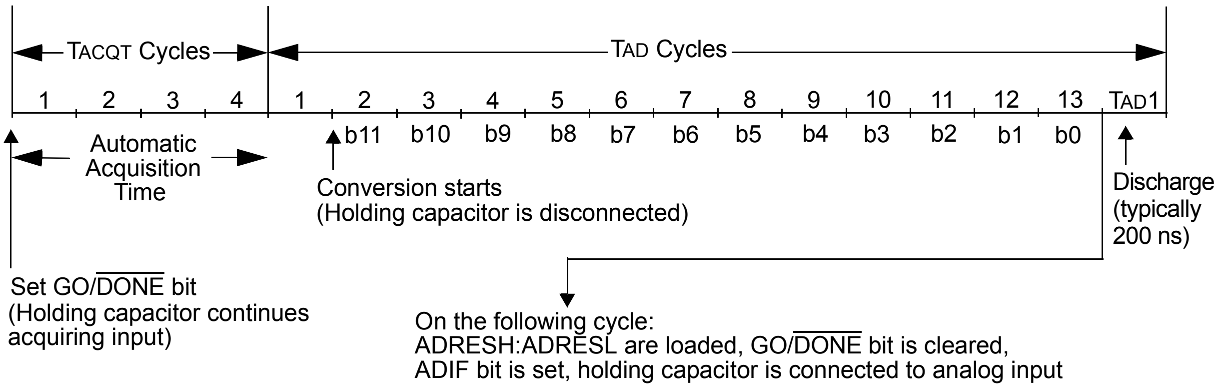


FIGURE 2-5: A/D CONVERSION TAD CYCLES (ACQT<2:0> = `010`, TACQ = 4 TAD)



2.8 Use of the ECCP2 Trigger

An A/D conversion can be started by the Special Event Trigger of the ECCP2 module. This requires that the CCP2M3:CCP2M0 bits (CCP2CON<3:0>) be programmed as ‘`1011`’ and that the A/D module is enabled (ADON bit is set). When the trigger occurs, the GO/$\overline{\text{DONE}}$ bit will be set, starting the A/D acquisition and conversion, and the Timer1 (or Timer3) counter will be reset to zero. Timer1 (or Timer3) is reset to automatically repeat the A/D acquisition period with minimal software overhead (moving ADRESH:ADRESL to the desired location). The appropriate analog input channel must be selected and the minimum acquisition period is either timed by the user, or an appropriate T_{ACQ} time selected before the Special Event Trigger sets the GO/$\overline{\text{DONE}}$ bit (starts a conversion).

If the A/D module is not enabled (ADON is cleared), the Special Event Trigger will be ignored by the A/D module but will still reset the Timer1 (or Timer3) counter.

TABLE 2-2: REGISTERS ASSOCIATED WITH A/D OPERATION

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Reset Values
INTCON	GIE/GIEH	PEIE/GIEL	TMR0IE	INT0IE	RBIE	TMR0IF	INT0IF	RBIF	(3)
PIR1	PSPIF	ADIF	RC1IF	TX1IF	SSP1IF	CCP1IF	TMR2IF	TMR1IF	(3)
PIE1	PSPIE	ADIE	RC1IE	TX1IE	SSP1IE	CCP1IE	TMR2IE	TMR1IE	(3)
IPR1	PSPIP	ADIP	RC1IP	TX1IP	SSP1IP	CCP1IP	TMR2IP	TMR1IP	(3)
PIR2	OSCFIF	CMIF	—	EEIF	BCL1IF	HLVDIF	TMR3IF	CCP2IF	(3)
PIE2	OSCFIE	CMIE	—	EEIE	BCL1IE	HLVDIE	TMR3IE	CCP2IE	(3)
IPR2	OSCFIP	CMIP	—	EEIP	BCL1IP	HLVDIP	TMR3IP	CCP2IP	(3)
ADRESH	A/D Result Register High Byte								(3)
ADRESL	A/D Result Register Low Byte								(3)
ADCON0	—	—	CHS3	CHS2	CHS1	CHS0	GO/$\overline{\text{DONE}}$	ADON	(3)
ADCON1	—	—	VCFG1	VCFG0	PCFG3	PCFG2	PCFG1	PCFG0	(3)
ADCON2	ADFM	—	ACQT2	ACQT1	ACQT0	ADCS2	ADCS1	ADCS0	(3)
TRISA	TRISA7(1)	TRISA6(1)	TRISA5	TRISA4	TRISA3	TRISA2	TRISA1	TRISA0	(3)
TRISF	TRISF7	TRISF6	TRISF5	TRISF4	TRISF3	TRISF2	TRISF1	TRISF0	(3)
TRISH(2)	TRISH7	TRISH6	TRISH5	TRISH4	TRISH3	TRISH2	TRISH1	TRISH0	(3)

Legend: — = unimplemented, read as ‘`0`’. Shaded cells are not used for A/D conversion.

Note 1: PORTA<7:6> and their direction bits are individually configured as port pins based on various primary oscillator modes. When disabled, these bits read as ‘`0`’.

2: These registers are not implemented on PIC18F6628/6723 devices.

3: For these Reset values, see the *“PIC18F8722 Family Data Sheet”* (DS39646).

4.0 ELECTRICAL CHARACTERISTICS

Note: Other than some basic data, this section documents only the PIC18F8723 family's specifications that differ from those of the PIC18F8722 family devices. For detailed information on the electrical specifications shared by the PIC18F8723 family and PIC18F8722 family devices, see the *"PIC18F8722 Family Data Sheet"* (DS39646).

Absolute Maximum Ratings(†)

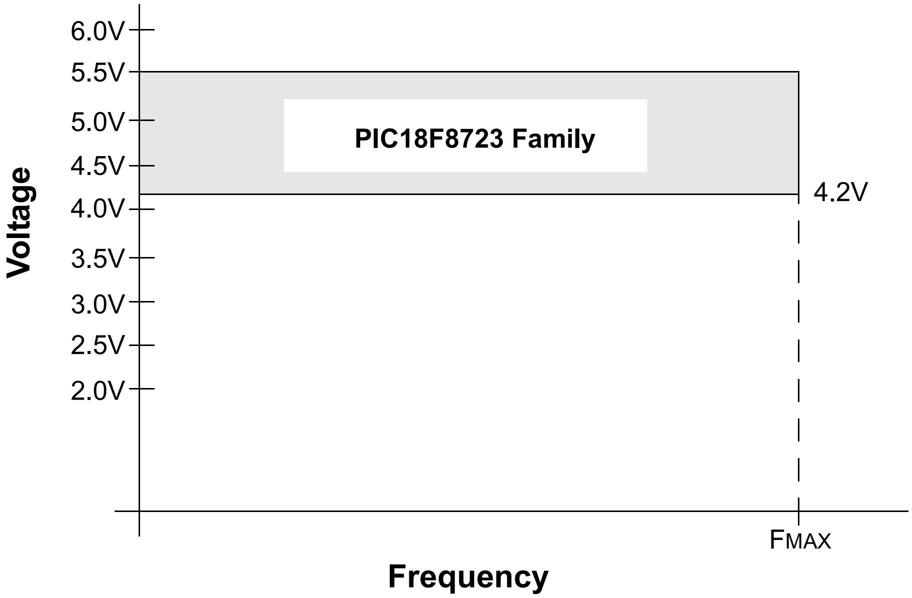
Ambient temperature under bias	-40°C to +125°C
Storage temperature	-65°C to +150°C
Voltage on any pin with respect to V_{SS} (except V_{DD} and $\overline{MCLR}$)	-0.3V to (V_{DD} + 0.3V)
Voltage on V_{DD} with respect to V_{SS}	-0.3V to +7.5V
Voltage on $\overline{MCLR}$ with respect to V_{SS} **(Note 2)**	0V to +13.25V
Total power dissipation **(Note 1)**	1.0W
Maximum current out of V_{SS} pin	300 mA
Maximum current into V_{DD} pin	250 mA
Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{DD}$)	±20 mA
Output clamp current, I_{OK} ($V_O < 0$ or $V_O > V_{DD}$)	±20 mA
Maximum output current sunk by any I/O pin	25 mA
Maximum output current sourced by any I/O pin	25 mA
Maximum current sunk by all ports	200 mA
Maximum current sourced by all ports	200 mA

Note 1: Power dissipation is calculated as follows:
$Pdis = V_{DD} \times \{I_{DD} - \sum I_{OH}\} + \sum \{(V_{DD} - V_{OH}) \times I_{OH}\} + \sum(V_{OL} \times I_{OL})$

2: Voltage spikes below V_{SS} at the RG5/$\overline{MCLR}$/V_{PP} pin, inducing currents greater than 80 mA, may cause latch-up. Thus, a series resistor of 50-100Ω should be used when applying a "low" level to the RG5/$\overline{MCLR}$/V_{PP} pin, rather than pulling this pin directly to V_{SS}.

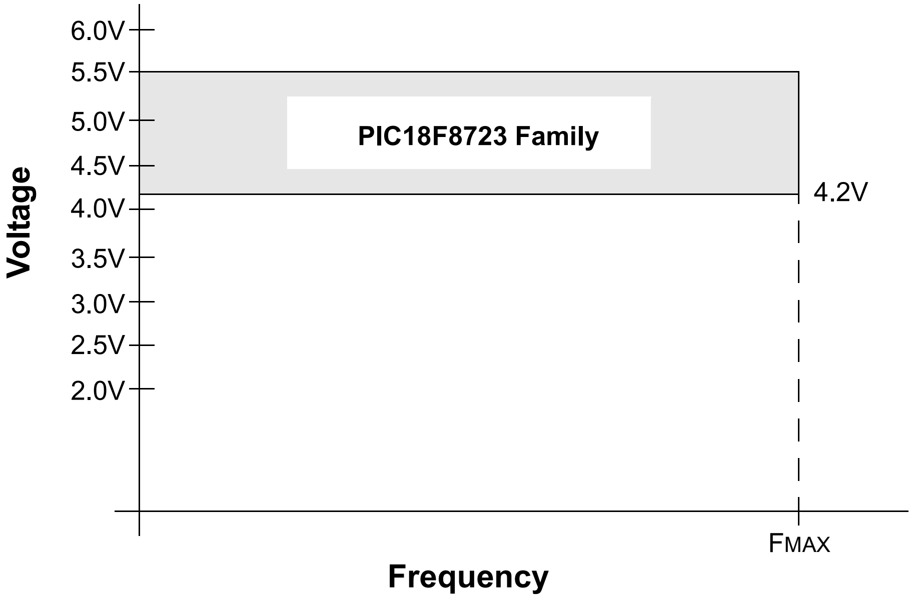
† **NOTICE:** Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operation listings of this specification is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

FIGURE 4-1: PIC18F8723 FAMILY VOLTAGE-FREQUENCY GRAPH (INDUSTRIAL)



FMAX = 20 MHz in 8-Bit External Memory mode.
FMAX = 40 MHz in all other modes.

FIGURE 4-2: PIC18F8723 FAMILY VOLTAGE-FREQUENCY GRAPH (EXTENDED)



FMAX = 20 MHz in 8-Bit External Memory mode.
FMAX = 25 MHz in all other modes.

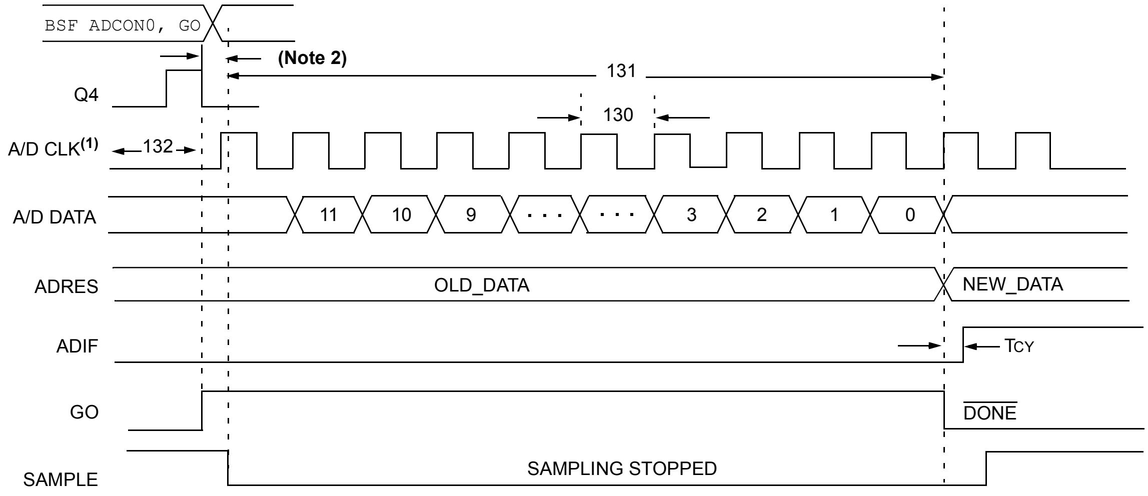
TABLE 4-1: A/D CONVERTER CHARACTERISTICS: PIC18F8723 FAMILY (INDUSTRIAL)

Param No.	Sym	Characteristic	Min	Typ	Max	Units	Conditions	
A01	NR	Resolution	—	—	12	bit		ΔVREF ≥ 3.0V
A03	EIL	Integral Linearity Error	—	<±1	±2.0	LSB	VDD = 3.0V	ΔVREF ≥ 3.0V
			—	—	±2.0	LSB	VDD = 5.0V	
A04	EDL	Differential Linearity Error	—	<±1	+1.5/-1.0	LSB	VDD = 3.0V	ΔVREF ≥ 3.0V
			—	—	+1.5/-1.0	LSB	VDD = 5.0V	
A06	EOFF	Offset Error	—	<±1	±5	LSB	VDD = 3.0V	ΔVREF ≥ 3.0V
			—	—	±3	LSB	VDD = 5.0V	
A07	EGN	Gain Error	—	<±1	±1.25	LSB	VDD = 3.0V	ΔVREF ≥ 3.0V
			—	—	±2.00	LSB	VDD = 5.0V	
A10	—	Monotonicity	Guaranteed(1)			—		VSS ≤ VAIN ≤ VREF
A20	ΔVREF	Reference Voltage Range (VREFH – VREFL)	3	—	VDD – VSS	V		For 12-bit resolution
A21	VREFH	Reference Voltage High	VSS + 3.0V	—	VDD + 0.3V	V		For 12-bit resolution
A22	VREFL	Reference Voltage Low	VSS – 0.3V	—	VDD – 3.0V	V		For 12-bit resolution
A25	VAIN	Analog Input Voltage	VREFL	—	VREFH	V		
A30	ZAIN	Recommended Impedance of Analog Voltage Source	—	—	2.5	kΩ		
A50	IREF	VREF Input Current(2)	— —	— —	5 150	μA μA		During VAIN acquisition. During A/D conversion cycle.

Note 1: The A/D conversion result never decreases with an increase in the input voltage and has no missing codes.

2: VREFH current is from the RA3/AN3/VREF+ pin or VDD, whichever is selected as the VREFH source. VREFL current is from the RA2/AN2/VREF-/CVREF pin or VSS, whichever is selected as the VREFL source.

FIGURE 4-4: A/D CONVERSION TIMING



Note 1: If the A/D clock source is selected as RC, a time of TCY is added before the A/D clock starts. This allows the `SLEEP` instruction to be executed.

2: This is a minimal RC delay (typically 100 ns), which also disconnects the holding capacitor from the analog input.

TABLE 4-2: A/D CONVERSION REQUIREMENTS

Param No.	Symbol	Characteristic		Min	Max	Units	Conditions
130	TAD	A/D Clock Period	PIC18**F**XXXX	0.8	12.5(1)	μs	TOSC based, VREF ≥ 3.0V
			PIC18**LF**XXXX	1.4	25.0(1)	μs	VDD = 3.0V; TOSC based, VREF full range
			PIC18**F**XXXX	—	1	μs	A/D RC mode
			PIC18**LF**XXXX	—	3	μs	VDD = 3.0V; A/D RC mode
131	TCNV	Conversion Time (not including acquisition time)(2)		13	14	TAD	
132	TACQ	Acquisition Time(3)		1.4	—	μs	
135	TSWC	Switching Time from Convert → Sample		—	**(Note 4)**		
137	TDIS	Discharge Time		0.2	—	μs	

Note 1: The time of the A/D clock period is dependent on the device frequency and the TAD clock divider.

2: ADRES registers may be read on the following TCY cycle.

3: The time for the holding capacitor to acquire the “New” input voltage when the voltage changes full scale after the conversion (VDD to VSS or VSS to VDD). The source impedance (RS) on the input channels is 50Ω.

4: On the following cycle of the device clock.

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